	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition
1	BRS	719	(adhesive near resin) with (chip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 10:55		
2	BRS	51	((adhesive near resin) with (chip or die) and tape and (ball or bump)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 10:56		
3	BRS	115	((adhesive near resin) with (chip or die) and tape	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 10:56		
4	BRS	83	(((adhesive near resin) with (chip or die)) and tape) and (water or vapor or moisture or porous or gap or stress)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 11:26		
5	BRS	1	"5703405".PN.	USPAT	2001/11/13 11:13		
6	BRS	1	"5604379".PN.	USPAT	2001/11/13 11:13		
7	BRS	1	"5352926".PN.	USPAT	2001/11/13 11:14		
8	BRS	23349	(water or vapor or moisture or porous or gap or stress)with tape)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 15:53		
9	BRS	21140	((water or vapor or moisture or porous or gap)with tape)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 11:42		
10	BRS	119	(((water or vapor or moisture or porous or gap or stress)with tape) and (adhesive adj resin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 11:30		
11	BRS	113	(((water or vapor or moisture or porous or gap or stress)with tape) and (adhesive adj resin)) not ((adhesive near resin) with (chip or die)) and tape)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 11:31		
12	BRS	35	(((water or vapor or moisture or porous or gap or stress)with tape) and (adhesive adj resin)) and (chip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 11:43		
13	BRS	1818	(water or vapor or moisture or porous or gap or stress)near tape)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 11:43		
14	BRS	35	(((water or vapor or moisture or porous or gap or stress)with tape) and (adhesive adj resin)) and (chip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 11:53		
15	BRS	0	(((((water or vapor or moisture or porous or gap or stress)with tape) and (adhesive adj resin)) and (chip or die)) NOT (((water or vapor or moisture or porous or gap or stress)with tape) and (adhesive adj resin)) and (chip or die))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 11:44		
16	BRS	2622	(POR$ OR GAP OR STRESS OR SPACE OR HOLE) NEAR TAPE	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 11:46		Truncation Overflow. Return string from Server is: 5`0`0`POR
17	BRS	420	((POR$ OR GAP OR STRESS OR SPACE OR HOLE) NEAR TAPE) and (chip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 15:49		
18	BRS	98	(((POR$ OR GAP OR STRESS OR SPACE OR HOLE) NEAR TAPE) and (chip or die)) AND ADHESIVE AND RESIN	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 11:52		
19	BRS	3579	((ball or bump) with tape)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 11:51		
20	BRS	381	((ball or bump) near tape)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 11:52		
21	BRS	81	(((ball or bump) near tape)) AND ADHESIVE AND RESIN	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 11:52		
22	BRS	73	((((ball or bump) near tape)) AND ADHESIVE AND RESIN) and (chip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 12:29		
23	IS&R	1	"5258330".PN.	USPAT	2001/11/13 12:29		

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
1	BRS	L3	13	(POR$ NEAR TAPE) and (chip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 15:51		Truncation Overflow. Return string from Server is: 5`0`0`POR	1
2	BRS	L4	10891	((water or vapor or moisture)with tape)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 15:54			0
3	BRS	L5	1217	L4 and (chip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 16:07			0
4	BRS	L6	597	L5 and (hole$ or porous or pore or gap)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 16:09		Truncation Overflow. Return string from Server is: 5`0`0`HOL	1
5	BRS	L7	248	L5 and ((hole$ or porous or pore or gap) with (tape or polyimide))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 16:30		Truncation Overflow. Return string from Server is: 5`0`0`HOL	1
6	BRS	L8	538	257/668.ccls. and (tape or polyimide)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 16:31			0
7	BRS	L9	132	L8 and (water or moisture or vapor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 16:32			0
8	BRS	L10	146	L8 and (water or moisture or vapor or crack)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 16:44			0

#	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
9	BRS	L11	44	257/736.ccls. and (water or moisture or vapor or crack)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 16:45			0
10	BRS	L12	300	257/737.ccls. and (water or moisture or vapor or crack)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 16:45			0
11	BRS	L13	235	257/738.ccls. and (water or moisture or vapor or crack)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 16:45			0
12	BRS	L14	123	257/719.ccls. and (water or moisture or vapor or crack)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 16:45			0
13	BRS	L15	312	257/778.ccls. and (water or moisture or vapor or crack)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 16:46			0
14	BRS	L16	201	257/783.ccls. and (water or moisture or vapor or crack)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 16:46			0
15	BRS	L17	171	257/678.ccls. and (water or moisture or vapor or crack)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 16:46			0
16	BRS	L18	184	257/668.ccls. and (water or moisture or vapor or crack)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 16:46			0

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
1	BRS	L3	13	(POR$ NEAR TAPE) and (chip or die)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/11/13 15:51		Truncation Overflow. Return string from Server is: 5`0`0`POR	1
2	BRS	L4	10891	((water or vapor or moisture)with tape)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/11/13 15:54			0
3	BRS	L5	1217	L4 and (chip or die)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/11/13 16:07			0
4	BRS	L6	597	L5 and (hole$ or porous or pore or gap)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/11/13 16:09		Truncation Overflow. Return string from Server is: 5`0`0`HOL	1
5	BRS	L7	248	L5 and ((hole$ or porous or pore or gap) with (tape or polyimide))	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/11/13 16:30		Truncation Overflow. Return string from Server is: 5`0`0`HOL	1
6	BRS	L8	538	257/668.ccls. and (tape or polyimide)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/11/13 16:31			0
7	BRS	L9	132	L8 and (water or moisture or vapor)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/11/13 16:32			0
8	BRS	L10	146	L8 and (water or moisture or vapor or crack)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/11/13 16:44			0

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
9	BRS	L11	44	257/736.ccls. and (water or moisture or vapor or crack)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 16:45			0
10	BRS	L12	300	257/737.ccls. and (water or moisture or vapor or crack)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 16:45			0
11	BRS	L13	235	257/738.ccls. and (water or moisture or vapor or crack)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 16:45			0
12	BRS	L14	123	257/719.ccls. and (water or moisture or vapor or crack)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 16:45			0
13	BRS	L15	312	257/778.ccls. and (water or moisture or vapor or crack)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 16:46			0
14	BRS	L16	201	257/783.ccls. and (water or moisture or vapor or crack)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 16:46			0
15	BRS	L17	171	257/678.ccls. and (water or moisture or vapor or crack)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 16:46			0
16	BRS	L18	184	257/668.ccls. and (water or moisture or vapor or crack)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 16:46			0
17	BRS	L19	1825	tape and (water adj (permeab$ or absorb$))	USPAT	2001/11/13 16:49			0
18	BRS	L20	431	L19 and (semiconductor or chip or die)	USPAT	2001/11/13 16:49			0

11/13/2001, EAST Version: 1.02.0008

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
19	BRS	L21	18	L19 and (g/m)	USPAT	2001/11/13 16:54			0
20	BRS	L22	25	(tape or resin) and ((water or moisture or vapor) with (g/m))	USPAT	2001/11/13 17:10			0
21	BRS	L23	28	((tape or resin) with (g/m)) and (water or moisture or vapor)	USPAT	2001/11/13 17:12			0
22	BRS	L24	2	(tape with (g/m)) and (semiconductor or chip or die)	USPAT	2001/11/13 17:09			0
23	BRS	L25	5	tape and ((water or moisture or vapor) with (g/m))	USPAT	2001/11/13 17:10			0
24	BRS	L26	7	L23 and ((semiconductor adj device) or chip or die)	USPAT	2001/11/13 17:12			0

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